

CHIP SCALE PACKAGE STRUCTURE FOR AN IMAGE SENSOR

BACKGROUND OF THE INVENTION

1. Field of the Invention

5 The present invention relates to a chip scale package structure, and more particularly to a chip scale package structure for an image sensor.

2. Description of Related Art

 The current package technology of an image sensor usually use
10 the ceramic leaded chip carrier (CLCC) or plastic leaded chip carrier (PLCC) that needs the processes of embedding a die pad and wire bonding. However, the number of I/O pins of an electric element become great, the thickness of the electric element becomes thin and the volume of the electric element becomes small under the requests of
15 a slight weight, multi-function and a quick process speed.
Consequently, the conventional solder technology is limited due to the diameter of the holes in the PCB for receiving the leads of electric parts. The surface mounting technology (SMT) is provided to overcome the problem of the conventional solder technology. However, the PCB
20 cannot be used to load the current thin lead such that the leads of electric parts are arranged in an array type for enhancing the yield of manufacturing. However, a hollow solder and a curve PCB is occurred after soldering according to great number I/O leads and a small

package volume. To solve the above problem is to lessen the volume of the jelly on the chip as small as possible.

As described above, the chip package technology trends toward Flip chip package. The process of flip chip package needs to grow
5 multiple bumps on the wafer and each bump is electrically connected to the circuit on a PCB such that the top of each of the bumps face the PCB and the prerequisite condition of a open sensing area of the image sensor is limited. Consequently, the flip chip has a good electric property, heat dissipation and a small packaged size, but it is difficult to
10 use the technology of flip chip on an image sensor very well.

A conventional flip chip package structure of an image sensor in accordance with the prior art shown in Fig. 7 comprises a glass plate (91) including an inner face forming a circuit (910) on the inner face of the glass plate (91) by etching. A chip (92) is soldered on the circuit
15 near a middle portion of the glass plate (91) by using first tin balls (93) and the technology of flip chip. The circuit (910) of the glass plate (91) has two opposite sides each having a second tin ball (94) for surface mounting of the circuit (910). The diameter of each of the second tin ball (94) must be greater than the thickness of the chip (92) for a good
20 reliability. For a suitable interval between the two second tin balls (94) the area of the glass plate (91) must be enlarged. Consequently, the enlarged glass plate (91) enlarges the volume of the image sensor. The type of the conventional flip chip package structure needs to be

advantageously altered.

The present invention has arisen to mitigate and/or obviate the disadvantages of the conventional flip chip package structure.

SUMMARY OF THE INVENTION

5 The main objective of the present invention is to provide an improved chip scale package (CSP) structure for an image sensor.

 To achieve the objective, the CSP structure in accordance with the present invention comprises a semi-conductor image sense chip and multiple bonding pads formed on a top face of the semi-conductor
10 image sense chip. A conducting wire extends from each of the multiple bonding pads by wire-bonding. Liquefied jelly-like material is covered with the top face of the semi-conductor image sense chip and forming a transparent layer on the top face of the semi-conductor image sense chip after drying up. The transparent layer has a thickness being equal
15 to a height of each of the conduct wire relative to the top face of the semi-conductor image sense chip.

 Further benefits and advantages of the present invention will become apparent after a careful reading of the detailed description with appropriate reference to the accompanying drawings.

20 BRIEF DESCRIPTION OF THE DRAWINGS

 Fig. 1 is a cross-sectional view of a chip scale package structure for an image sensor in accordance with the present invention;

 Fig. 2 is a cross-sectional schematic view of the chip scale

package structure in Fig. 1 for showing the chip scale package structure used in an image sensor;

Fig. 3 is an exploded perspective view of the schematic embodiment of the chip scale package structure in fig. 2;

5 Fig. 4 is a bottom plan view of a flexible printed circuit of the chip scale package structure of the present invention;

Fig. 5 is a cross-sectional view of a second embodiment of the chip scale package structure for an image sensor in accordance with the present invention;

10 Fig. 6 is a cross-sectional schematic view of the chip scale package structure in Fig. 5 for showing the chip scale package structure used in an image sensor; and

Fig. 7 is a cross-sectional view of a conventional flip chip package structure in accordance with the prior art.

15 DETAILED DESCRIPTION OF THE INVENTION

Referring to the drawings and initially to Fig. 1, a chip scale package (CSP) structure (1) for an image sensor in accordance with the present invention comprises semi-conductor image sense chip (10) having multiple bonding pads (11) disposed in a top face of the semi-conductor image sense chip (10). A conduct wire (12) extends
20 from each of the bonding pads (11) by a wire-bonding machine.

The top face of the semi-conductor image sense chip (10) is coated by liquefied jelly-like material that forms a transparent layer (13)

after drying up. The transparent layer (13) has a top face (131) that is ground and burnished to form a plane (P1) that is parallel to the top face of the semi-conductor image sense chip (10). The transparent layer (13) has a thickness being equal to a height of each of the conduct
5 wires (12) relative to the top face of the semi-conductor image sense chip (10). The transparent layer (13) has a periphery covered by a shelter (132) to prevent the light from laterally penetrating into the chip scale package structure and influencing the quality of the images that is collected by the chip scale package structure.

10 According to the SCP structure (1) of the present invention, the manufacturing processes of chip scale package are simplified. The manufacturer can bond the conduct wire (12) and form the transparent layer (13) before dividing the wafer. The wafer is divided after forming the plane (P1) and the manufacturing processes of CSP are finished.

15 Furthermore, the manufacturing processes of a convention flip chip, such as forming a leadframe, forming a substrate, wire bonding and mounting a glass plate, are unnecessary to the chip scale package structure of the present invention. Consequently, the manufacturing cost of the present invention is effectively reduced, especially to a
20 secondary image sensor.

With reference to Figs. 2 and 3, the chip scale package structure in accordance with the present invention is provided to an image sense module. A metal solder ball (14) is planted on a free end of each of the

conduct wires (12) and electrically connected to a flexible printed circuit (FPC) (20). The FPC has a window (22) defined therein and corresponding to a sensing area of the semi-conductor image sense chip (10) and a conducting circuit (21) form on a bottom face of the FPC. With reference to Fig. 4, the conducting circuit (21) includes multiple first solder points (211) formed near a periphery of the window (22). The number of the first solder points (211) corresponds to that of the conduct wire (12). The conducting circuit (21) includes multiple second solder points (212) formed near one side of the FPC (20) and arranged in an array.

The image sense module includes a lens set (30) attached to the top face of the FPC (20). The lens set (30) includes a holder (31) having a skirt (311) downward extending from the holder (31) around the semi-conductor image sense chip (10). The holder (31) includes a channel (312) defined in one side of the skirt (311) to allow the FPC (20) extending the holder (31).

The above image sense module, the plane (P1) of the transparent layer (13) can provide a good datum for the holder (31) for the light axis perpendicularly projecting to the semi-conductor image sense chip (10), and the skirt (31) can accurately position the semi-conductor image sense chip (10) for controlling the image collect area located in a lens projecting area that has a low image fault.

With reference to Fig. 5 that shows a second embodiment of the

CSP structure for an image sensor in accordance with the present invention, the CSP structure (4) includes a semi-conductor image sense chip (40) having multiple bumps (41) formed on a top face of the semi-conductor image sense chip (40). A transparent glass plate (42) is
5 attached to the top face of the semi-conductor image sense chip (40). The transparent glass plate (42) has an area being equal to that of the semi-conductor image sense chip (40) and a thickness being equal to that of each of the bumps (41). The transparent glass plate (42) includes multiple penetration holes (421) defined therein. Each
10 penetration hole (421) aligns with a corresponding one of the multiple bumps (41) such that each bump (41) extends to a top face of the transparent glass plate (42). The transparent glass plate (42) has a periphery covered by a shelter (422) to prevent the light from laterally penetrating into the chip scale package structure and influencing the
15 quality of the images that is collected by the chip scale package structure.

With reference to Fig. 6, the CSP structure (4), as shown in Fig. 5, is provided to an image sense module. A metal solder ball (43) is planted on a free end of each of the multiple bumps (41) and
20 electrically connected to a flexible printed circuit (FPC) (20). The FPC has a window (22) defined therein and corresponding to a sensing area of the semi-conductor image sense chip (40) and a conducting circuit (21). With reference to Fig. 4, the conducting circuit (21) includes first

solder points (211) formed near a periphery of the window (22). The number of the first solder points (211) corresponds to that of the bumps (41). The conducting circuit (21) includes multiple second solder points (212) formed near one side of the FPC (20).

5 The image sense module includes a lens set (30) attached to the top face of the FPC (20). The lens set (30) includes a holder (31) having a skirt (311) downward extending from the holder (31) around the semi-conductor image sense chip (40). The holder (31) includes a channel (312) defined in one side of the skirt (311) to allow the FPC
10 (20) extending the holder (31).

 The transparent glass plate (42) of the second embodiment is used to replace the transparent layer (13) of the first embodiment of the present invention because the transparent layer (13) needs to be ground and burnished.

15 Although the invention has been explained in relation to its preferred embodiment, it is to be understood that many other possible modifications and variations can be made without departing from the spirit and scope of the invention as hereinafter claimed.